

Product End-of-Life Disassembly Instructions

Product Name / Model: DT Research Rugged Convertible Laptop / LT330

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of DT Research products to remove components and materials requiring selective treatment, as defined by EU Directive 2012/19/EU of the European Parliament and of the Council of 4 July 2012 on waste electrical and electronic equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards Assemblies (PCBA)	With a surface greater than 10 sq cm	1
Mass storage device	Permanently soldered to PCBA	0
Batteries	All types including standard alkaline and lithium coin or button style batteries	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches,	0
LCD Display	a surface greater than 100 sq cm includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and	Include the cartridges, print heads, tubes, vent chambers, and service	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Philips screwdriver	
Description #2 Slotted screwdriver	
Description #3 Hex screwdriver	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

- (1) Dismantle system.
- (2) Dismantle enclosure B.
- (3) Dismantle enclosure C.
- (4) Dismantle enclosure D.
- (5) Dismantle enclosure A.
- (6) Dismantle PCBA.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

- (1) Dismantle system



LT330 拆解步骤—系统(5)



LT330 拆解步骤—系统(6)



LT330 拆解步骤—系统(7)



LT330 拆解步骤—系统(8)



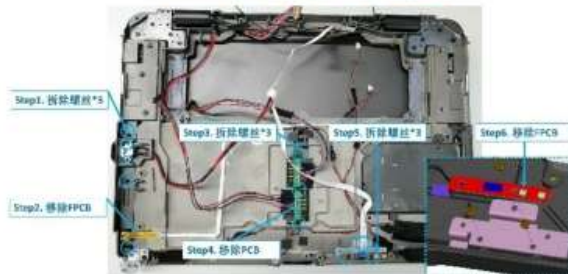
LT330 拆解步骤—系统(9)



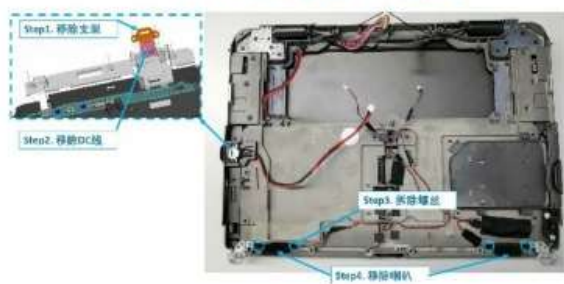
LT330 拆解步骤—系统(10)



LT330 拆解步骤—系统(11)



LT330 拆解步骤—系统(12)



LT330 拆解步骤—系统(13)



LT330 拆解步骤—系统(14)



(2) Dismantle enclosure B

LT330 拆解步骤—B壳(1)



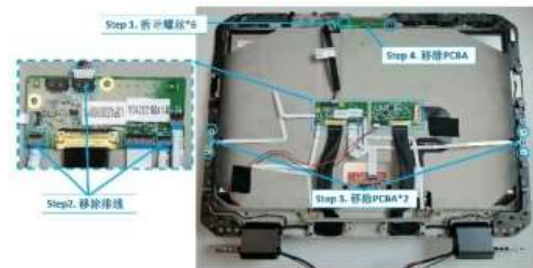
LT330 拆解步骤—B壳(2)



LT330 拆解步骤—B壳(3)



LT330 拆解步骤—B壳(4)



LT330 拆解步骤—B壳(5)



LT330 拆解步骤—B壳(6)



LT330 拆解步骤—B壳(7)



(3) Dismantle enclosure C

LT330 拆解步骤—C壳(1)



LT330 拆解步骤—C壳(2)



LT330 拆解步骤—C壳(3)



(4) Dismantle enclosure D

LT330 拆解步骤—D壳(1)



LT330 拆解步骤—D壳(2)



LT330 拆解步骤—D壳(3)



LT330 拆解步骤—D壳(4)



(5) Dismantle enclosure A

LT330 拆解步骤—A壳 (1)



LT330 拆解步骤—A壳 (2)



(6) Dismantle PCBA

LT330 拆解步骤—主板

